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Part Number:

0737801223

Status:

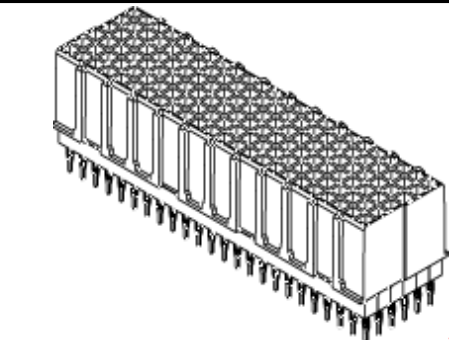
Active

Overview:

[hdm](#)

Description:

2.00mm (.079") Pitch HDM® Board-to-Board Daughtercard Receptacle, Vertical, Signal Module, 144 Circuits, Mounted Height 13.00mm (.512"), Pin Length 2.50mm (.098"), Solder Tail



Series
image - Reference only

Documents:

- [3D Model](#)
- [Drawing \(PDF\)](#)
- [Test Summary \(PDF\)](#)
- [Product Specification PS-73780-999 \(PDF\)](#)
- [RoHS Certificate of Compliance \(PDF\)](#)

General

Product Family	Backplane Connectors
Series	73780
Application	Daughtercard, Mezzanine
Comments	Solder Tail
Component Type	PCB Receptacle
Overview	hdm
Product Name	HDM®
Style	N/A

Physical

Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Copper-Nickel-Tin
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length (in)	0.079 In
PC Tail Length (mm)	2.00 mm
PCB Locator	No
PCB Retention	None
PCB Thickness Recommended (in)	0.063 In
PCB Thickness Recommended (mm)	1.60 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Pitch - Term. Interface (in)	0.079 In
Pitch - Term. Interface (mm)	2.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	100
Plating min: Termination (µm)	2.5
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes

EU RoHS

ELV and RoHS
Compliant

REACH SVHC

Contains SVHC: No

Halogen-Free

Status

Not Reviewed

China RoHS

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[73780Series](#)

Mates With
HDM® Board-to-Board Backplane Header [73642](#) , [73643](#) , [73644](#) , [73942](#) , [73943](#) , [73944](#) , [74349](#) , [74428](#). HDM® Board-to-Board Stacking Header [73769](#) , [73770](#) , [73782](#) , [73783](#) , [73771](#)

Temperature Range - Operating

Termination Interface: Style

-55°C to +105°C

Through Hole

Electrical

Current - Maximum per Contact

Data Rate

Real Signals (per 25mm)

Shielded

Voltage - Maximum

15A, 1A

1.0 Gbps

75

No

250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)

Lead-free Process Capability

Max. Cycles at Max. Process Temperature

Process Temperature max. C

5

Wave Capable (TH only)

1

260

Material Info

Reference - Drawing Numbers

Product Specification

Sales Drawing

PS-73780-999

SD-73780-004

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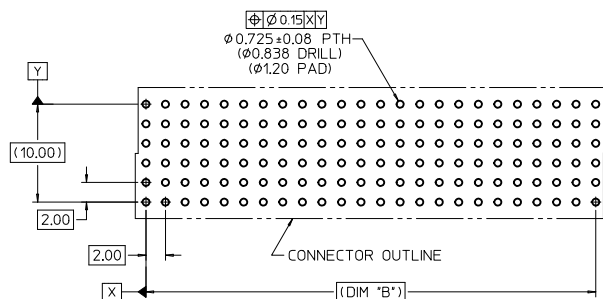
MATERIAL NUMBER ASSIGNMENT



NOTES:

1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK
2. FINISH: SELECTIVE GOLD (Au) IN CONTACT AREA, .76 MICROMETER MINIMUM THICKNESS, SELECTIVE TIN (Sn), 2.50 MINIMUM THICKNESS ON SOLDER TAILS, NICKEL (Ni) OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73780-999.
4. MARKINGS SHOWN FOR REFERENCE ONLY. SEE MATERIAL NUMBER ASSIGNMENT DIAGRAM FOR CORRECT NUMBER. MARKINGS TO INCLUDE MATERIAL NUMBER AND DATE CODE AND CAN BE LOCATED ANYWHERE ON PART, IN ANY ORIENTATION.
5. 73780-***7 AND -***0* PARTS TO BE PACKAGED IN TUBES PER PK-70873-0872. ALL OTHER PARTS TO BE PACKAGED IN TUBES PER PK-70873-0900.
6. 144-CIRCUIT HDM DAUGHTERCARD STACKING MODULE WITH PRESS-FIT TAILS SHOWN FOR ILLUSTRATION PURPOSES ONLY.
7. TRUE POSITION OF PC TAILS IS INSPECTED USING GAUGE NUMBER 73727-0014.
8. MARKINGS MAY BE ORIENTED TO EITHER SIDE OF CONNECTOR.

PCB LAYOUT: COMPONENT SIDE



73780-1***	144	48.17	46.00	47.6
73780-0***	72	24.17	22.00	23.6
MATERIAL NUMBER	CIRCUIT SIZE	DIM "A"	DIM "B"	DIM "C"

UPDATE TO S.T. ONLY		QUALITY SYMBOLS		GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE		DESIGN UNITS		THIRD ANGLE PROJECTION	
IEC NO: UCP2010-1860		DRAWN: J. MELTON 2010/01/22		4 PLACES ±		MM ONLY		4:1		METRIC		⊙ □ THIRD ANGLE PROJECTION	
DRAWING NO: 2010/01/22		CHECKED: S. DANIELLEY 05/07/08		3 PLACES ±		DATE		TITLE		SALES ASSEMBLY, HDM DAUGHTERCARD STACKING MODULE, SOLDER TAIL			
APPROVED: MILLER 2010/02/08		DESCRIPTION		2 PLACES ± 0.05		BSMART 05/07/08		MOLEX		MOLEX INCORPORATED			
				1 PLACE ± 0.10		APPROVED BY DATE		DOCUMENT NO.		SD-73780-004			
				ANGULAR ± 2 °		MILLER 2010/02/08		SHEET NO.		1 OF 1			
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
						SIZE D							